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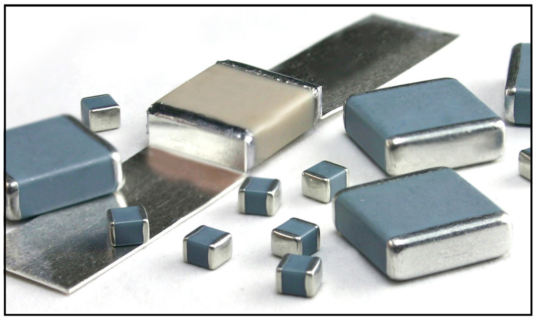
DLI•Novacap•Syfer•Voltronics

DLI DIELECTRIC LABORATORIES

NEW!

MLCs with Copper Barrier, Plated Finishes for Non-Magnetic Applications

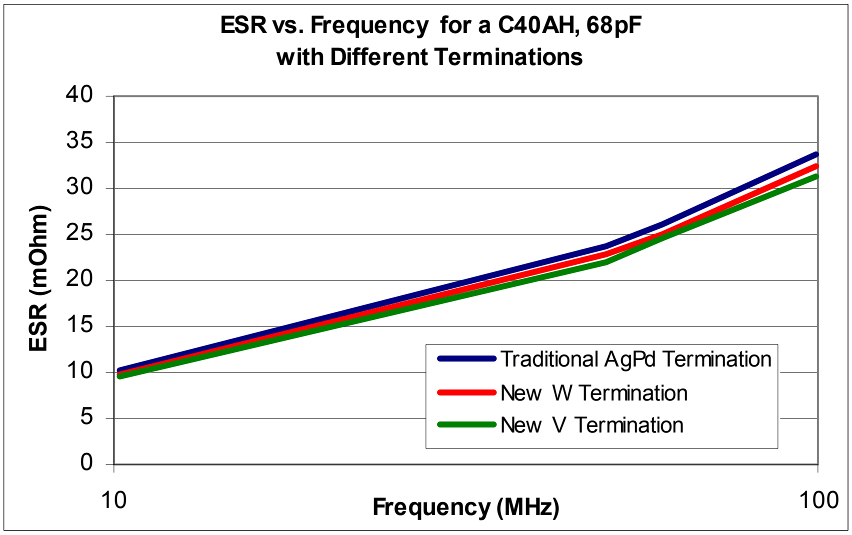


DLI has released four new termination options for use in MRI, NMR, military, and other magnetic field sensitive applications.

'W' termination is an RoHS compliant plated tin finish MLC suitable for high-volume assembly. ***'V' termination*** offers a more traditional tin-lead finish, while our ***'R' termination*** provides a heavy tin-lead coating for high reliability, hand soldering applications. These three options are based on DLI's proven silver adhesion layer, now with a copper solder barrier. The new ***'M' termination*** consists of an RoHS compliant tin solder plate finish over a flexible polymer-silver termination, available in spring of 2007. As a member of our Flexi-Q™ family of MLCs, this system reduces stresses that contribute to cracking during board-mounting and that result from board flexure in the field.

Rugged by design!

DLI's new non-magnetic termination finishes offer improved durability over multiple rework cycles. In applications requiring tuning or multiple reflows, ***our copper barrier non-magnetic finishes withstand up to three times more process cycles*** than the traditional silver-palladium finishes. When subjected to multiple solder stress cycles (10 second full immersion), the copper barrier finishes average six cycles until solder wetting is degraded, similar to our nickel barrier line of MLCs.



Renowned electrical performance!

DLI's new W, V, R, and M terminations offer the ***same low ESR, tight TC, and high power handling characteristics*** as our other high performance MLCs. These new finishes are available in our porcelain AH (P90) material system, our ultra-stable CF (NP0) material system, and our ultra-low ESR UL (NP0) material system.

▶ **W** (RoHS) Ag adhesion layer, 400-500 µ-in Cu barrier, 200 µ-in Sn plate
Available w/AH & CF systems (UL spring 2007) ● Radial, axial, center ribbon leads standard

▶ **V** Ag adhesion layer, 400-500 µ-in Cu barrier, 100-150 µ-in 90/10 Sn/Pb plate
Available w/AH & CF systems (UL spring 2007) ● Radial, axial, center ribbon leads standard

▶ **R** Ag adhesion layer, 400-500 µ-in Cu barrier, 10-12 mils 90/10 Sn/Pb plate
Available w/AH & CF systems (UL spring 2007)

▶ **M** (RoHS) Polymer/Ag adhesion layer, 400-500 µ-in Cu barrier, 200 µ-in Sn plate
Available w/AH & CF systems (UL spring 2007) ● Radial, axial, center ribbon leads standard

Ask us! We are tight tolerance, custom requirement specialists. All new finishes are available in a broad range of custom lead and assembly configurations.

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